

- Spectral response 7–14 μ m
- Operating temperature range -40°C to + 95°C
- Array operability > 99%
- Digital video output on LVDS interface
- TEC less operation
- Weight \leq 5 g
- Overall dimension (mm) 25x25x2
- Material Si/SiGe mono-crystalline quantum well
- Array format 384 x 288 pixels
- Pixel pitch 25 μ m
- NETD <20mK
- Thermal time constant < 12 ms



Sensoror will offer non-cooled and TEC (Thermo-Electric-Cooler) less bolometer focal plane arrays (FPA's) for High Precision applications. The solution is based on a unique Si/SiGe mono-crystalline quantum well structure used as the temperature-sensing (thermistor) membrane of the pixels. The TCR (temperature coefficient of resistance) of this material surpasses today's available technologies and at the same time the mono-crystalline grain boundary free material secures superior 1/f noise performance. This novel pixel technology is coupled with Sensoror's wafer bonding experience to offer the combination of

the best signal-noise ratio and the best reliability at the lowest cost.

Sensoror has a close cooperation with Acreo to optimize the bolometer technology and both parties are as well involved in common EU funded programs aiming to bring this innovative solution into industry.

PARTNERS

Acreo AB www.acreo.com

PIMS (Pedestrian Injury Mitigation System) www.autoliv.com

FNIR (Fusing Far and Near Infra Red imaging for pedestrian injury mitigation) www.fnir.nu

ICU (Infrared Imaging Components for Use in Automotive Safety Applications) www.icu-eu.com